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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10070000	FILING DATE 11/27/2002	CLASS 205	SUBCLASS 21	GAU 1741	EXAMINER Wong
**APPLICANTS: Hu Jung-Chih; Gau Wu-Chun; Chang Ting-Chang; Feng Ming-Shiann; Cheng Chun-Lin; Lin You-Shin; Li Ying-Hao; Chen Lih-Juann;					
**CONTINUING DATA VERIFIED: This application is a 371 of PCT/EP00/08312 08/25/2000					
** FOREIGN APPLICATIONS VERIFIED: GERMANY 199 41 605.2 09/01/1999					
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PG-PUB <input type="checkbox"/>		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed		<input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO	
35 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no		MERCK 2395	
Verified and Acknowledged Examiners's initials					
TITLE : Galvanizing solution for the galvanic deposition of copper					
<small>U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)</small>					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED		
		Assistant Examiner	Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner	DRAWING	
Amount Due	Date Paid		Sheets Drwg.	Figs. Drwg.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Application Examiner	
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